

Abstract

A device and a method are proposed for determining the extent of an at least locally lateral undercut of a structured surface layer (23) on a sacrificial layer (21). The structured surface layer (23) for this purpose locally has at least one passive electronic component (31), using which a physical measured quantity can be determined, which is proportional to the extent of the lateral undercut. The method according to the present invention for generating this device proposes, initially on the structured surface layer (23) in a first etching method, to provide the surface layer (21) at least locally with a structuring having trenches (15') and, in a second etching method, proceeding from the trenches (15'), to undertake at least locally a lateral undercut of the structured surface layer (23). In this context, in the first etching method on the surface layer (23), locally at least one passive electronic component (31) is additionally delineated out, which in response to a subsequent undercutting of the surface layer (23) is also undercut. The physical measured quantity is determined without contact, preferably by sending an electromagnetic emission into the passive component (31).

Figure 3